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## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

re application of

Akihisa HONGO et al.

Serial No. 09/762,582

Attn: Application Branch

Filed April 12, 2001

Attorney Docket No. 2001\_0133A

## SUBSTRATE PLATING METHOD AND APPARATUS

REQUEST FOR CORRECTION OF PATENT OFFICE RECORDSAssistant Commissioner for Patents,  
Washington, DC 20231

Sir:

The title of the invention indicated on the official filing receipt reflects the title used in the international application. Accordingly, please correct the official Patent Office records to reflect the title indicated in the declaration and specification, i.e.

--SUBSTRATE PLATING METHOD AND APPARATUS--

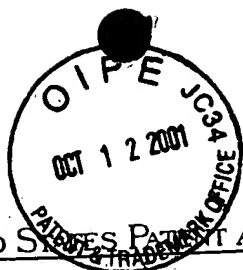
A corrected filing receipt is requested in the above-referenced case. A copy of the original filing receipt is enclosed, with the changes noted thereon.

Respectfully submitted,

Akihisa HONGO et al.

By

Michael S. Huppert  
Registration No. 40,268  
Attorney for ApplicantsMSH/kjf  
Washington, D.C. 20006-1021  
Telephone (202) 721-8200  
Facsimile (202) 721-8250  
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APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO	DRAWINGS	TOT CLAIMS	IND CLAIMS
09/762,582	04/12/2001	1741	1044	2001-0133A	18	11	3

CONFIRMATION NO. 5731

CORRECTED FILING RECEIPT



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 000513  
 WENDEROTH, LIND & PONACK, L.L.P.  
 2033 K STREET N. W.  
 SUITE 800  
 WASHINGTON, DC 20006-1021

Date Mailed: 09/11/2001

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

## Applicant(s)

 Akihisa Hongo, Tokyo, JAPAN;  
 Naoaki Ogure, Tokyo, JAPAN;  
 Hiroaki Inoue, Tokyo, JAPAN;  
 Satoshi Sendai, Tokyo, JAPAN;  
 Tetsuma Ikegami, Tokyo, JAPAN;  
 Koji Mishima, Tokyo, JAPAN;  
 Shuichi Okuyama, Tokyo, JAPAN;  
 Mizuki Nagai, Tokyo, JAPAN;  
 Ryoichi Kimizuka, Tokyo, JAPAN;  
 Megumi Maruyama, Kanagawa, JAPAN;

## Domestic Priority data as claimed by applicant

THIS APPLICATION IS A 371 OF PCT/JP99/04349 08/11/1999

## Foreign Applications

 JAPAN 10-239490 08/11/1998  
 JAPAN 11-30230 02/08/1999  
 JAPAN 11-220363 08/03/1999

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Projected Publication Date: N/A

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Early Publication Request: No

Title

Substrate Plating Method and Apparatus  
~~Wafer plating method and apparatus~~

Preliminary Class

205

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Data entry by : HINES, BRENDA

Team : 1700

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